

General

	Rev	Cage Code
 Vectron® Oscillators	E	00136

This specification defines the design, assembly, and functional evaluation of high reliability, Space qualified, hybrid clock oscillators produced by Microchip. Devices delivered to this specification represent the standardized Parts, Materials and Processes (PMP) Program developed, implemented, and certified for advanced applications and extended environments.

For more information see [Space Oscillators](#).

For technical support regarding this Hi-Rel Standard, please contact VOP-Support@microchip.com.

Applications Overview

The designs represented by these products were primarily developed for the MIL-Aerospace community. The lesser Design Pedigrees and Screening Options imbedded within DOC207975 bridge the gap between Space and COTS hardware by providing custom hardware with measures of mechanical, assembly and reliability assurance needed for Military or Ruggedized COTS environments.

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1. Applicable Documents

1.1. Specifications and Standards

The following specifications and standards form a part of this document to the extent specified herein. The issue currently in effect on the date of quotation will be the product baseline, unless otherwise specified. In the event of conflict between the texts of any references cited herein, the text of this document shall take precedence.

Table 1-1. Military

Document	Title
MIL-PRF-55310	Oscillators, Crystal Controlled, General Specification For
MIL-PRF-38534	Hybrid Microcircuits, General Specification For

Table 1-2. Standards

Document	Title
MIL-STD-202	Test Method Standard, Electronic and Electrical Component Parts
MIL-STD-883	Test Methods and Procedures for Microelectronics

Table 1-3. Other

Document	Title
DOC207984	Test Specification, Hybrid Clock, Hi-Rel Standard, SINE Output
QSP-91502	Procedure for Electrostatic Discharge Precautions
QSP-90100	Quality Systems Manual, Microchip
DOC011627	Identification Common Documents, Materials and Processes, Hi-Rel XO
DOC203982	DPA Specification
DOC208191	Enhanced Element Evaluation for Space Level Hybrid Oscillators
DOC220429	Packaging Standards, Hi-Rel Series

2. General Requirements

2.1. Classification

All devices delivered to this specification are of hybrid technology conforming to Type 1, Class 2 of MIL-PRF-55310. Primarily developed as a Class S equivalent specification, options are imbedded within it to also produce Class B, Engineering Model and Ruggedized COTS devices. Devices carry a Class 2 ESDS classification per MIL-PRF-38534.

2.2. Item Identification

Unique model number series are utilized to identify device package configurations as listed in [Table 6-1](#).

2.3. Absolute Maximum Ratings

Parameter	Value
Supply Voltage Range (V_{CC})	0 Vdc to $V_{CC} + 2.0$ Vdc
Storage Temperature Range (T_{STG})	-65 °C to +125 °C
Junction Temperature (T_J)	+175 °C
Lead Temperature (Soldering, 10 seconds)	+300 °C

2.4. Design, Parts, Materials and Processes, Assembly, Inspection and Test

2.4.1. Design

The ruggedized designs implemented for these devices are proven in military and space applications under extreme environments. Designs utilize 4-point crystal mounting in combination with Established Reliability (MIL-ER) components where possible. When specified, radiation tolerant active devices up to 300 krad (Si) (RHA level R) are met by utilizing swept quartz and active device types that have passed testing to that level.

2.4.1.1. Design and Configuration Stability

Barring changes to improve performance by reselecting passive chip component values to offset component tolerances, there will not be fundamental changes to the design or assembly or parts, materials and processes after first product delivery of that item without notification.

2.4.1.2. Environmental Integrity

Designs have passed the environmental qualification levels of MIL-PRF-55310. These designs have also passed extended dynamic levels of at least:

- Sine Vibration: MIL-STD-202, Method 204, Condition G (30g pk.)
- Random Vibration: MIL-STD-202, Method 214, Condition II-J (43.92g rms, three-minute duration in each of three mutually perpendicular directions)
- Mechanical Shock: MIL-STD-202, Method 213, Condition F (1500g, 0.5 ms)

2.4.2. Prohibited Parts, Materials and Processes

The items listed are prohibited for use in high reliability devices produced to this specification.

- a. Gold metallization of package elements without a barrier metal.
- b. Zinc chromate as a finish.
- c. Cadmium, zinc, or pure tin external or internal to the device.
- d. Plastic encapsulated semiconductor devices.
- e. Ultrasonically cleaned electronic parts.
- f. Heterojunction Bipolar Transistor (HBT) technology.
- g. 'Getter' materials

2.4.3. Assembly

Manufacturing utilizes standardized procedures, processes, and verification methods to produce MIL-PRF-55310 Class S/MIL-PRF-38534 Class K equivalent devices. MIL-PRF-38534 Group B Option 1 in-line inspection is included on radiation hardened part numbers to further verify lot pedigree. Devices are handled in accordance with Microchip document QSP-91502 (Procedure for Electrostatic Discharge Precautions). Element replacement will be as specified in MIL-PRF-38534, Rev L.

2.4.4. Inspection

The inspection requirements of MIL-PRF-55310 apply to all devices delivered to this document. Inspection conditions and standards are documented in accordance with the Quality Assurance, ISO-9001 and AS9100 derived, System of QSP-90100.

2.4.5. Test

The Screening test matrix of [Table 6-5](#) is tailored for selectable-combination testing to eliminate costs associated with the development/maintenance of device-specific documentation packages while maintaining performance integrity.

2.4.6. Marking

Device marking shall be in accordance with the requirements of MIL-PRF-55310. In addition, when devices are identified with laser marking, the Resistance to Solvents test specified in MIL-PRF-55310 Group C, MIL-PRF-55310 Qualification or MIL-PRF-38534 Group B Inspection will not be performed.

2.4.7. Ruggedized COTS Design Implementation

Design Pedigree "D" devices (see [4.2. Optional Design, Test and Data Parameters](#)) use the same robust designs found in the other device pedigrees. They do not include the provisions of traceability or the Class-qualified components noted in paragraphs [2.4.3. Assembly](#) and [3.1. Components](#).

3. Detail Requirements

3.1. Components

3.1.1. Crystals

Cultured quartz crystal resonators are used to provide the selected frequency for the devices. The optional use of Premium Q swept quartz can, because of its processing to remove impurities, be specified to minimize frequency drift when operating in radiation environments. In accordance with MIL-PRF-55310, the manufacturer has a documented crystal element evaluation program.

3.1.2. Passive Components

3.1.2.1. Design Pedigree E

Where available, resistors shall be Established Reliability, Failure Rate R (as a minimum) and capacitors shall be Failure Rate S. Where resistors and capacitors are not available as ER parts, and for all other passive components, the parts shall be from homogeneous manufacturing lots that have successfully completed the Enhanced Element Evaluation of DOC208191 which meets the requirements of MIL-PRF-38534 Revision L for Class K.

3.1.2.2. Design Pedigrees F, V, and X

Where available, resistors shall be Established Reliability, Failure Rate R (as a minimum) and capacitors shall be Failure Rate S. Where resistors and capacitors are not available as ER parts, and for all other passive components, the parts shall be from homogeneous manufacturing lots that have successfully completed the Class K Element Evaluation of MIL-PRF-38534 Revision K for Class K.

3.1.2.3. Design Pedigrees B and C

All passive elements shall comply with the Element Evaluation requirements of MIL-PRF-55310 Class B as a minimum.

3.1.2.4. Design Pedigree D

Passive elements will be COTS level or higher.

3.1.2.5. Inductors

When used, inductors will be open construction and may use up to 47-gauge wire.

3.1.3. Semiconductors (Transistor)

3.1.3.1. Design Pedigree E

Semiconductors shall be from homogeneous wafer lots that meet the Enhanced Element Evaluation requirements in DOC208191.

3.1.3.2. Design Pedigrees F, V, and X

Semiconductors shall be from homogeneous wafer lots that have successfully completed the MIL-PRF-38534, Revision K Lot Acceptance Tests for Class K devices as a minimum.

3.1.3.3. Design Pedigrees B and C

Semiconductors are procured from wafer lots that have successfully completed the MIL-PRF-55310 Lot Acceptance Tests for Class B devices as a minimum.

3.1.3.4. Design Pedigree D

Semiconductors can be COTS level or higher.

3.1.4. Radiation

When optionally specified, further testing is performed on the bipolar transistor for radiation hardness assurance up to 300 krad (Si) total ionizing dose (TID). In addition, the transistor used in the 1700 series has been tested in similar oscillators with a differential output to an LET greater than 83 MeV-cm²/mg and did not have any significant transients that perturbed through subsequent differential driver circuitry to the output of the oscillator tested.

3.1.5. Packages

Packages are procured that meet the construction, lead materials and finishes as specified in MIL-PRF-55310. All leads are Kovar with gold plating over a nickel underplate. Package lots are evaluated in accordance with the requirements of MIL-PRF-38534. Microchip will not perform Salt Spray testing as part of MIL-PRF-55310 Group C/Qualification. In addition, we perform Terminal Strength testing per MIL-STD-202, Method 211, Test Condition C with following exceptions: Load shall be 3 oz ± 0.3 oz, three bends at 90°.

3.1.6. Traceability and Homogeneity

All design pedigrees except option D have active device lots that are homogenous and traceable to the manufacturer's individual wafer; all other elements and materials are traceable to their manufacturer and incoming inspection lots. Design pedigrees E, F, V and X have homogeneous material. In addition, swept quartz crystals are traceable to the quartz bar and the processing details of the autoclave lot. A production lot, as defined by Microchip, is all oscillators that have been kitted and built as a single group. The maximum deliverable quantity with a single lot date code is 150 units. Order quantities that exceed 150 units will be delivered in multiple lot date codes with deliveries separated by 3 weeks. If applicable, each production lot will be kitted with homogeneous material which is then allocated across multiple lot date code builds to satisfy the deliverable order quantity. When ordered, Group C Inspection, lot qualifications, and/or DPA will be performed on the first build lot within the production lot unless otherwise stated on the purchase order.

3.2. Mechanical

3.2.1. Package Outline

[Table 6-1](#) links each Hi-Rel Standard Model Number of this specification to a corresponding package style. Mechanical outline information of each package style is found in the referenced figure.

3.2.2. Thermal Characteristics

The calculated thermal resistance and resulting junction temperature rise is found in [Table 6-4](#).

3.2.3. Lead Forming

When the lead forming option is specified, the applicable leak test specified in screening will be performed after forming.

3.3. Electrical

3.3.1. Input Power

Devices are designed for standard +3.3Vdc, +5.0Vdc, or +12Vdc, (±5%). Current is measured at maximum rated operating voltage.

3.3.2. Temperature Range

Operating range is -55 °C to +125 °C.

3.3.3. Frequency Tolerance

Initial accuracy at +23 °C is ±15 ppm maximum. Frequency-Temperature Stability is ±50 ppm maximum from +23 °C reference. Frequency-Voltage Tolerance is ±4 ppm maximum.

3.3.4. Frequency Aging

Aging limits, and when tested in accordance with MIL-PRF-55310 Group B inspection, shall not exceed ± 1.5 ppm the first 30 days, ± 5 ppm Year 1 and ± 2 ppm per year thereafter.

3.3.4.1. Frequency Aging Duration Option

For Screening Option S, the Aging test will be terminated after 15 days if the measured aging rate is less than half of the specified aging rate. This is a common method of expediting 30-day Aging without incurring risk to the hardware and used quite successfully for numerous customers. It is based on the 'least squares fit' determinations of MIL-PRF-55310 paragraph 4.8.35. The 'half the time/half the spec' limit is generally conservative as roughly 2/3 of a unit's Aging deviation occurs within that period of time. Microchip's automated aging systems take about 6 data points per day, so a large amount of data is available to do very accurate projections, much more data than what is required by MIL-PRF-55310. The delivered data includes the Aging plots projected to 30 days. If the units do not perform within that limit, then they continue to the full 30-day term. For all other screening options, please make a note on the purchase order if this is an acceptable option as it assists in job planning and minimizes lead time.

3.3.5. Operating Characteristics

Sinewave output limits are dependent on the device frequency and supply voltage and are in accordance with [Table 6-2](#). Start-up time is 10.0 ms maximum.

3.3.6. Output Load

Output load is 50 Ω to ground.

4. Quality Assurance Provisions and Verification

4.1. Verification and Test

Device lots shall be tested prior to delivery in accordance with the applicable Screening Option letter as stated by the 15th character of the part number. [Table 6-5](#) tests are conducted in the order shown and annotated on the appropriate process travelers and data sheets of the governing test procedure. For devices that require Screening Options that include MIL-PRF-55310 Group A testing, the Post-Burn-In Electrical Test and the Group A Electrical Test are combined into one operation.

4.1.1. Screening Options

The Screening Options, by letter, are summarized as:

Table 4-1. Screening Options

Screening Option	Description
A	Modified MIL-PRF-38534 Class K Screening
B	Modified MIL-PRF-55310 Class B Screening & Group A QCI
C	Modified MIL-PRF-55310 (Rev E) Class S Screening & Group A QCI
D	Modified MIL-PRF-38534 Class K Screening & 30-day Aging
E	Modified MIL-PRF-55310 Class B Screening & Groups A & B QCI
F	Modified MIL-PRF-55310 (Rev E) Class S Screening & Groups A & B QCI
G	Modified MIL-PRF-55310 Class B Screening & Post BI Nominal Electricals
S	MIL-PRF-55310 (Rev F) Class S Screening & Groups A & B QCI
X	Engineering Model (EM)

4.2. Optional Design, Test and Data Parameters

The following is a list of design, assembly, inspection, and test options that can be selected or added by purchase order request.

Design Pedigree (choose one as the 5th character in the part number):

Table 4-2. Design Pedigree

Design Pedigree	Description
E	Enhanced Element Evaluation (MIL-PRF-38534 Rev L for Class K components as specified in DOC208191), 300 krad die, Premium Q Swept Quartz
F	Hi-Rel design with 300 krad Class K die, Premium Q Swept Quartz
V	Hi-Rel design with 300 krad Class K die, Non-Swept Quartz
X	Hi-Rel design with Non-Swept Quartz, Class K die
B	Hi-Rel design with Premium Q Swept Quartz, Class B die
C	Hi-Rel design with Non-Swept Quartz, Class B die
D	Hi-Rel design with Non-Swept Quartz and commercial grade components

b. Input Voltage as the 14th character. See [Ordering Part Number](#).

c. Not Used

d. Radiographic Inspection

e. Group C Inspection: In accordance with (IAW) MIL-PRF-55310, Rev E (requires 8 destruct specimens)

f. Group C Inspection: IAW MIL-PRF-55310, Rev F (requires 8 destruct specimens, includes Random Vibration, MIL-STD-883, Method 1014 Leak Test and Life Test)

g. Group C Inspection: IAW MIL-PRF-38534, Table C-Xc, Condition PI [requires 8 destruct specimens – Life (5), RGA (3)]. Subgroup 1 fine leak test to be performed per MIL-STD-202, Method 112, Condition C.

h. Internal Water-Vapor Content (RGA) samples and test performance

i. MTBF Reliability Calculations: IAW MIL-HDBK-217 unless otherwise specified

j. Worst Case Analysis: IAW MIL-HDBK-1547 unless otherwise specified

k. Derating and Thermal Analysis (unless otherwise specified, MIL-HDBK-1547 with $T_j \text{ Max} = +105^\circ\text{C}$; Derated Maximum Operating Temp = $T_j \text{ Max} - \Delta T_j$)

l. Process Identification Documentation (PID)

m. Customer Source Inspection (pre-crystal mount pre-cap, post-crystal mount pre-cap and final). Due to components being mounted underneath the crystal blank, pre-crystal mount pre-cap inspection should be considered.

n. Destruct Physical Analysis (DPA): IAW MIL-STD-1580 with exceptions as specified in Microchip DOC203982. The DPA leak test specified will agree with the screening option selected.

o. Qualification: IAW MIL-PRF-55310, Rev F, Table IV (requires 16 destruct specimens). Includes Group III, SG1 through SG6 only. ESD (SG7) not performed.

p. Qualification: IAW EEE-INST-002, Section C4, Table 3, Level 1 or 2 (requires 11 destruct specimens)

q. High Resolution Digital Pre-Cap Photographs (20 Megapixels minimum)

r. Hot solder dip of leads with Sn63/Pb37 solder prior to shipping.

s. As Designed Parts, Materials and Processes List

4.2.1. NASA EEE-INST-002 Compliance

A combination of Design Pedigree F, Option S Screening, and performance of Qualification per EEE-INST-002, Section C4, Table 3 on 11 destruct specimens, meet the requirements of Level 1 and Level 2 device reliability.

4.3. Test Conditions

Unless otherwise stated herein, inspections are performed in accordance with those specified in MIL-PRF-55310. Process travelers identify the applicable methods, conditions, and procedures to be used. Examples of electrical test procedures that correspond to MIL-PRF-55310 requirements are shown in [Table 6-3](#).

4.4. Deliverable Data

The manufacturer supplies the following data, as a minimum, with each lot of devices:

- a. As applicable to the Screening Option chosen, completed assembly and screening lot travelers, screening data, including radiographic images, and rework history.
- b. Electrical test variables data, identified by unique serial number.
- c. Special items when required by purchase order such as Group C, DPA, and RGA data. Unless otherwise specified on purchase order, all destruct specimens will be shipped. As delivered, all destruct specimens will be identified by subgroup (if applicable) and packaged separately from flight units.
- d. For Design Pedigrees E, F, V, and X, traceability, component LAT, enclosure LAT, and wafer lot specific RLAT data for non-SMD active devices (if applicable).
- e. Certificate of Conformance.

4.5. Discrepant Material

All MRB authority resides with the procuring activity.

4.6. Failure Analysis

Any failure during Qualification or Group C Inspection will be evaluated for root cause. The customer will be notified after occurrence and upon completion of the evaluation.

5. Preparation for Delivery

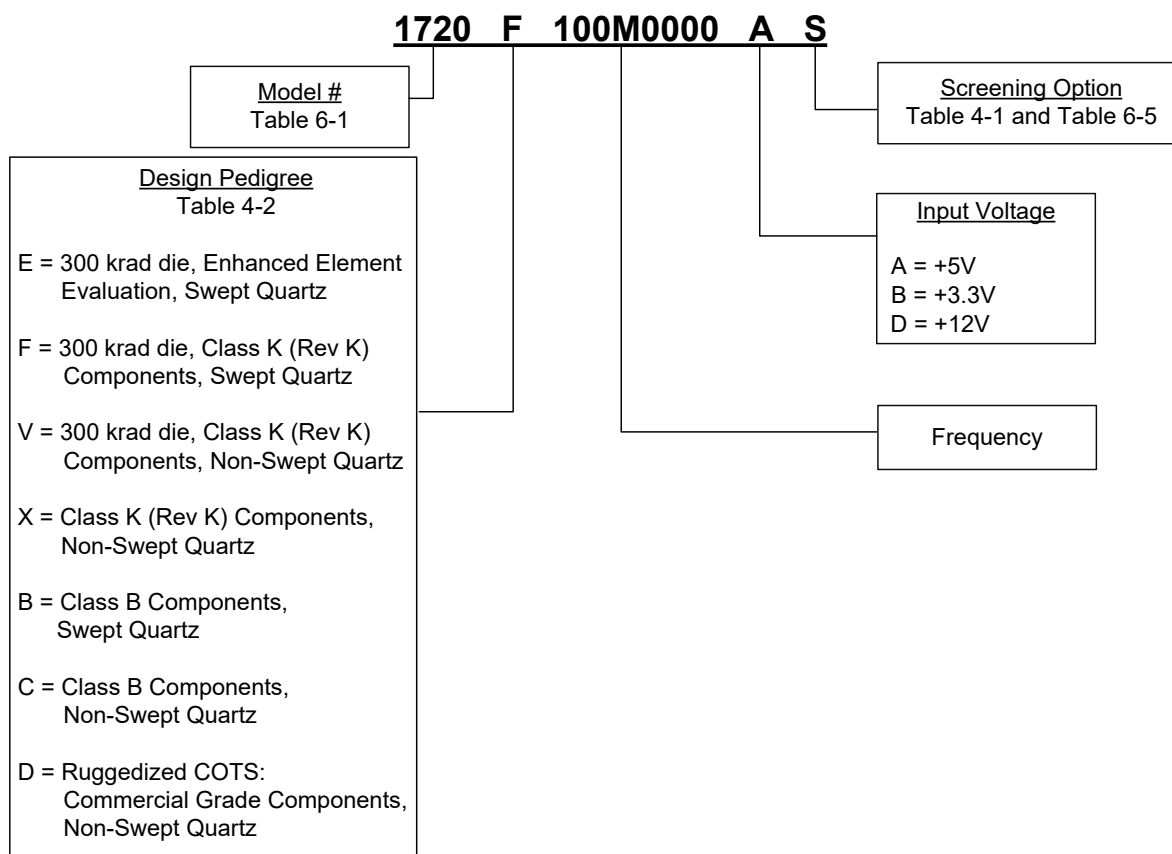
5.1. Packaging

Devices will be packaged in a manner that prevents handling and transit damage during shipping. Devices will be handled in accordance with ANSI/ESD S20.20. Devices will be packaged for transport in accordance with DOC220429. Please note that “one unit per package” is available for a fee; however, this service must be requested as part of the official RFQ.

6. Ordering Information

6.1. Ordering Part Number

The ordering part number consists of an alphanumeric string of 15 continuous characters, without spaces.



6.1.1. Model Number

The device model number is the four (4) digit number assigned to a corresponding package and output combination per [Table 6-1](#).

6.1.2. Design Pedigree

Class S designs are identified by the letters "E," "F," "V," or "X," while Class B designs are indicated by either the letter "B" or "C". Ruggedized COTS, which utilize commercial grade components, are designated by the letter "D".

6.1.3. Output Frequency

The nominal output frequency is expressed in the format as specified in MIL-PRF-55310 utilizing eight (8) total characters. (Example: 12 MHz = 12M00000, 200 MHz = 200M0000)

6.1.4. Input Voltage

Voltage is the 14th character.

6.1.5. Screening Options

The 15th character is the Screening Option (letter A through G, S or X) selected from [Table 6-5](#).

6.2. Electrical Characteristics and Test Parameters

Optional test and documentation requirements shall be specified by separate purchase order line items (as listed in [4.2. Optional Design, Test and Data Parameters](#)).

Table 6-1. Item Identification and Package Outline

Model #	Package	Mechanical Outline and I/O Connections ²
1704	20 Lead Flatpack	Figure 6-3
1720 ¹	20 Lead Flatpack	Figure 6-4
1719	16 Lead Flatpack	Figure 6-5
1721 ¹	16 Lead Flatpack	Figure 6-6
Notes:		
1. Models 1720 and 1721 are lead-formed versions of Models 1704 and 1719 respectively. See 7. Recommended Land Patterns for recommended land patterns.		
2. All unassigned pins have no internal connections or ties. We recommend all unassigned pins be tied to ground. Lids are internally tied to case ground.		

Table 6-2. Electrical Performance Characteristics

Parameter	Value
Frequency Range	12 MHz to 200 MHz (16x16 mm, 20-pin FP) >200 MHz to 500 MHz (25x25 mm, 16-pin FP)
Temperature Range	-55 °C to +125 °C
Frequency Tolerance, Initial Accuracy at +23 °C	±15 ppm max.
Frequency-Temperature Stability from +23 °C Ref.	±50 ppm max.
Frequency-Voltage Tolerance	±4 ppm max. (Vcc ±5%)
Frequency Aging	±1.5 ppm max. 1 st 30 days, ±5 ppm max. Year 1, ±2 ppm max. Year 2+ (Estimated maximum aging for 20 years will be <10 ppm due to the non-linear characteristics of crystal aging)
Start-up Time	10.0 ms max.
Harmonics	-20 dBc max.
Non-Harmonic Spurious	-80 dBc max. ¹
Phase Noise	See Figure 6-1 and Figure 6-2 .

Frequency Range (MHz)	Vcc ± 5% (V)	Input Current at max Vcc (mA max)	Output Power (dBm min)	Subharmonics (dBc max)
12-200	+3.3	20	+3	—
	+5.0	20	+5	—
	+12.0	20	+7	—
> 200-500	+3.3	35	+3	-30
	+5.0	35	+5	-30
	+12.0	35	+7	-30

Note:

1. Met by design and not tested.

Table 6-3. Electrical Test Parameters

Operation Listing	Requirements and Conditions
PERFORMED DURING ALL ELECTRICAL TESTS	
Input Current (no load)	MIL-PRF-55310, Para 4.8.5.1
Initial Accuracy at Reference Temperature	MIL-PRF-55310, Para 4.8.6
Output Power	MIL-PRF-55310, Para 4.8.21.2
Harmonics/Subharmonics	
PERFORMED DURING POST BURN-IN ELECTRICAL ONLY	
Overvoltage Survivability	MIL-PRF-55310, Para 4.8.4
Initial Frequency-Temperature Accuracy	MIL-PRF-55310, Para 4.8.10.1
Frequency-Voltage Tolerance	MIL-PRF-55310, Para 4.8.14
Start-up Time	MIL-PRF-55310, Para 4.8.29

Table 6-4. Thermal Characteristics and Weight

Model #	Thermal Resistance Junction to Case θ_{jc} (°C/W)	Worst Case Δ Junction Temperature T_j (°C @ max power)	Typical Weight (grams)
16x16 mm, 20-pin FP	14.3	3.4	3.0
25x25 mm, 16-pin FP	15.1	6.0	7.5

Note: The maximum current and voltage from Table 6-2 is used to calculate the worst case Δ junction temperature for the model series.

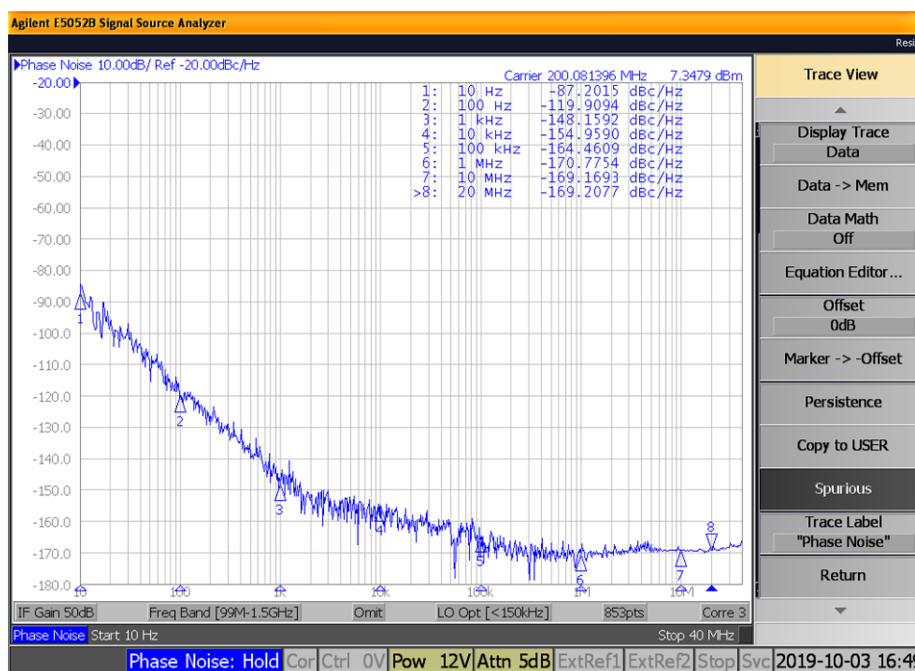
Figure 6-1. Typical Phase Noise at 200 MHz 12V


Figure 6-2. Typical Phase Noise at 500 MHz 3.3V

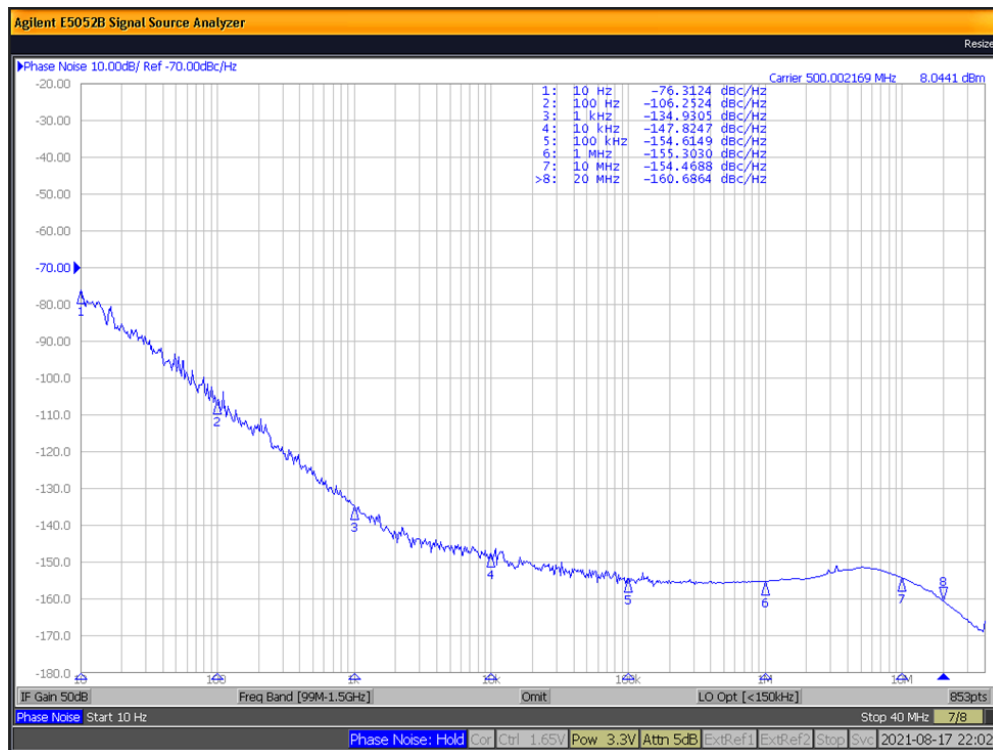


Table 6-5. Test Matrix

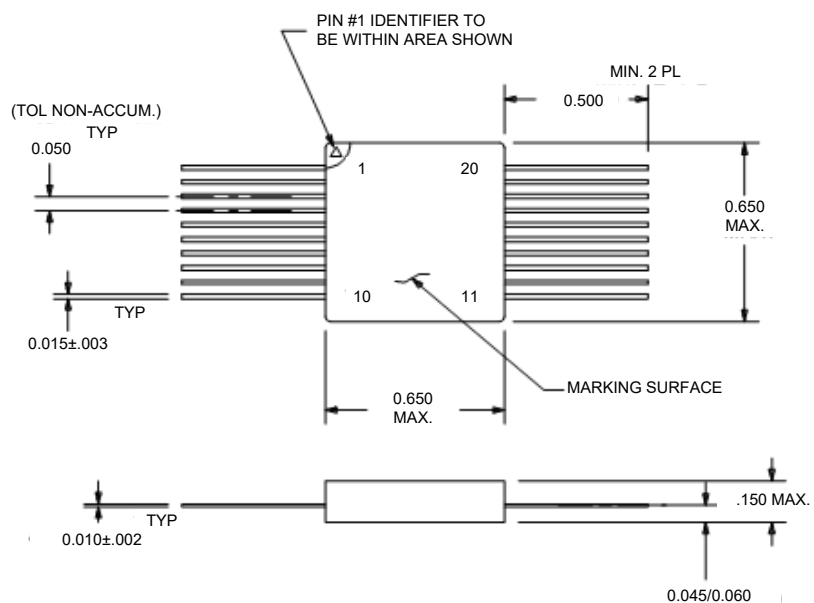
OPN. NO.	Operation Listing	Requirements and Conditions	Option A	Option B	Option C	Option D	Option E	Option F	Option G	Option S	Option X
	SCREENING	MIL Class Similarity (MIL-PRF-55310, Class S/B or MIL-PRF-38534, Class K)	K 100%	B- 100%	S- 100%	K+ 100%	B 100%	S (Rev E) 100%	— 100%	S (Rev F) 100%	EM 100%
1	Non-Destruct Bond Pull	MIL-STD-883, Method 2023	X	NR	X	X	NR	X	NR	X	NR
2	Internal Visual	MIL-STD-883, Method 2017 Class K, Method 2032 Class K	X	X	X	X	X	X	X	X	X
3	Stabilization (Vacuum) Bake	MIL-STD-883, Method 1008, Cond. C, 150°C	X 48 hrs.	X 24 hrs.	X 48 hrs.	X 48 hrs.	X 24 hrs.	X 48 hrs.	X 24 hrs.	X 48 hrs.	X 24 hrs.
4	Random Vibration	MIL-STD-883, Method 2026, Cond. I-B, 15 mins in each axis	NR	NR	NR	NR	NR	NR	NR	X	NR
5	Thermal Shock	MIL-STD-883, Method 1011, Cond. A	NR	NR	X	NR	NR	X	NR	X	NR
6	Temperature Cycle	MIL-STD-883, Method 1010, Cond. B (except Option S), 10 cycles min.	X	X	X	X	X	X	X	X Cond. C	NR
7	Constant Acceleration	MIL-STD-883, Method 2001, Cond. A,Y1 plane only, 5000g	X	X	X	X	X	X	X	X	NR
8	Particle Impact Noise Detection	MIL-STD-883, Method 2020, Cond. B (except Option S)	X	X	X	X	X	X	NR	X Cond. A	X ⁴
9	Electrical Testing, Pre Burn-In	Perform tests in Table 6-3 . Nominal Vcc, nominal temperature	X	X	X	X	X	X	X	X	X
10	1 st Burn-In	MIL-STD-883, Method 1015, Cond. B	X 160 hrs.	X 160 hrs.	X 240 hrs.	X 160 hrs.	X 160 hrs.	X 240 hrs.	X 160 hrs.	X 240 hrs.	NR
11	Electrical Testing, Intermediate	Perform tests in Table 6-3 . Nominal Vcc, nominal temperature	X	NR	NR	X	NR	NR	NR	NR	NR
12	2 nd Burn-In	MIL-STD-883, Method 1015, Cond. B	X 160 hrs.	NR	NR	X 160 hrs.	NR	NR	NR	NR	NR
13	Electrical Testing, Post Burn-In (Group A) ⁴	Perform tests in Table 6-3 . Nominal Vcc and extremes, nominal temperature and extremes	X	X	X	X	X	X	X nom. Vcc	X	NR
14	Seal: Fine Leak	MIL-STD-202, Method 112, Cond. C (5 x 10 ⁻⁸ atm cc/sec max)	X	X	X	X	X	X	X	NR	X
	Seal: Gross Leak	MIL-STD-202, Method 112, Cond. D									
15	Seal: Fine Leak	MIL-STD-883, Method 1014, Cond. A2 or B1	NR	NR	NR	NR	NR	NR	NR	X	NR
	Seal: Gross Leak	MIL-STD-883, Method 1014, Cond. B2 or B3									
16	Radiographic Inspection	MIL-STD-883, Method 1012	X	AR	AR	X	AR	X	NR	X	NR
17	Solderability	MIL-STD-883, Method 2003	1	1	1	1	1	1	1	1	NR
18	External Visual and Mechanical	MIL-STD-883, Method 2009	X ²	X ²	X ²	X ²	X ²	X ²	X ²	X ²	X ²
19	Aging, 30 Day ³ (M55310 Group B)	MIL-PRF-55310, para. 4.8.35.1	NR	NR	NR	X	13 pcs.	X	NR	X	NR
20	Group C Inspection (optional)	See 4.2. Optional Design, Test and Data Parameters for details of supplier recommended Group C Inspection options	4.2(g)	4.2(e)	4.2(e)	4.2(g)	4.2(e)	4.2(e)	4.2(e)	4.2(f)	NR

Legend: X = Required, NR = Not Required, AR = As Required

Notes:

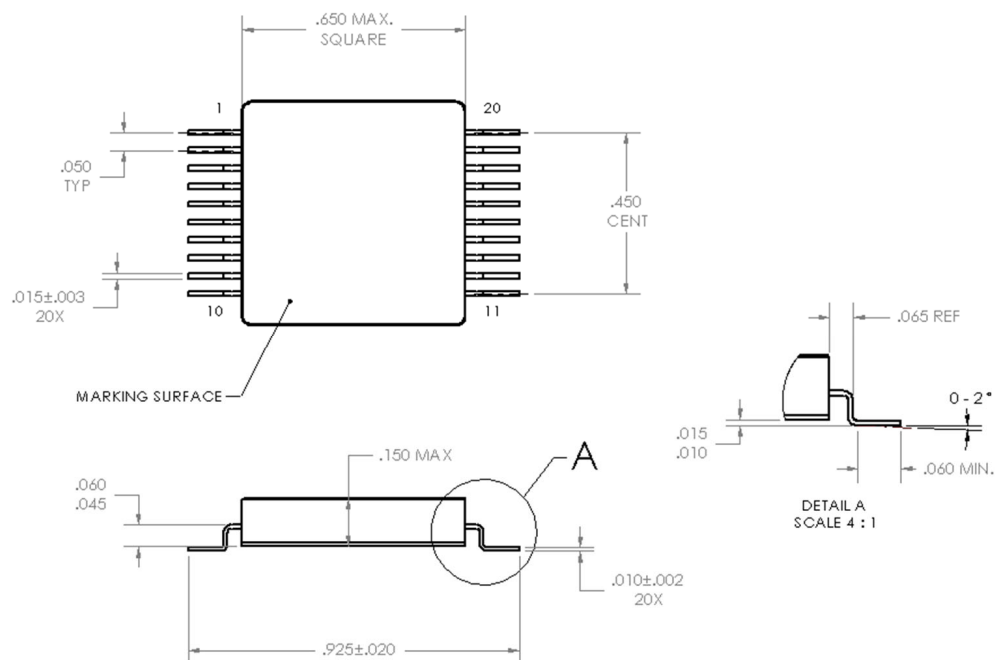
- Performed at package LAT. Include LAT data sheet.
- When specified, RGA samples will be removed from the lot after completion of this operation. Use of Screening failures require customer concurrence.
- See [3.3.4.1. Frequency Aging Duration Option](#).
- PIND PDA does not apply.

Figure 6-3. Model 1704 Package Outline and I/O Connections



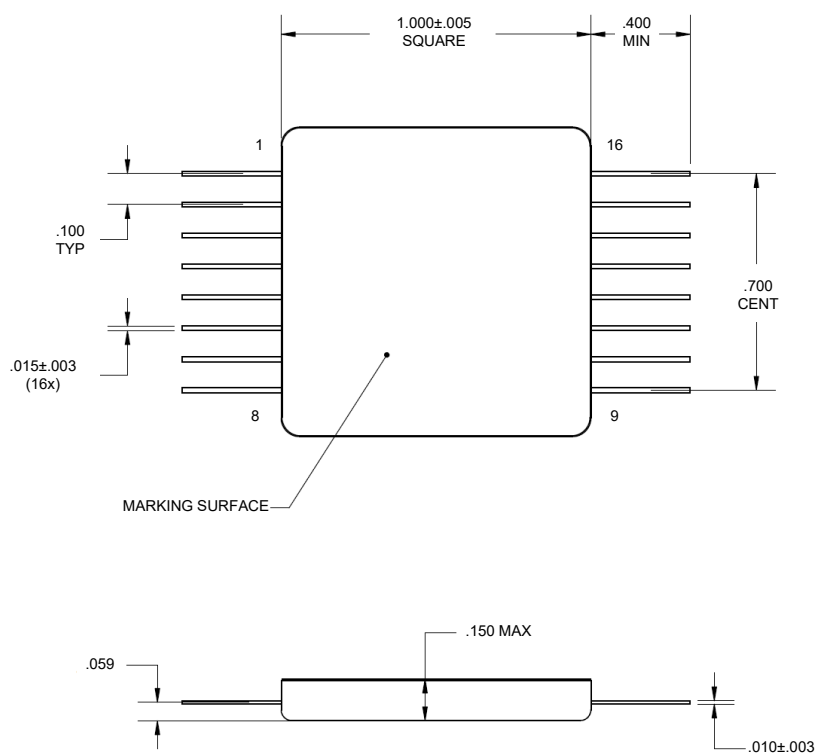
Model #	I/O Connections		
	Vcc	Output	Gnd/Case
1704	20	11	10

Figure 6-4. Model 1720 Package Outline and I/O Connection



Model #	I/O Connections		
	Vcc	Output	Gnd/Case
1720	20	11	10

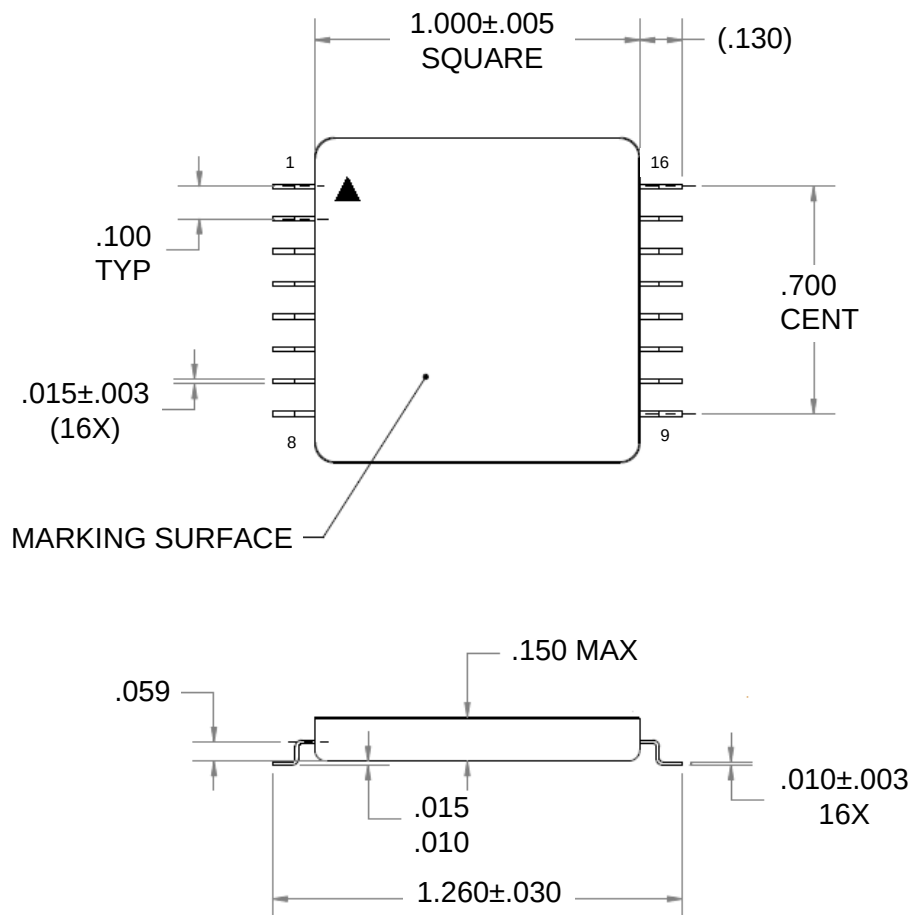
Figure 6-5. Model 1719 Package Outline and I/O Connections



Model #	I/O Connections		
	Vcc	Output	Gnd/Case
1719	16	9	8, 11

Note: Tolerance (unless otherwise specified): XXX± .005 [.130], XX± .01 [.25]

Figure 6-6. Model 1721 Package Outline and I/O Connections



Model #	I/O Connections		
	Vcc	Output	Gnd/Case
1721	16	9	8, 11

Note: Tolerance (unless otherwise specified): XXX± .005 [.130], XX± .01 [.25]

7. Recommended Land Patterns

Figure 7-1. Model 1720

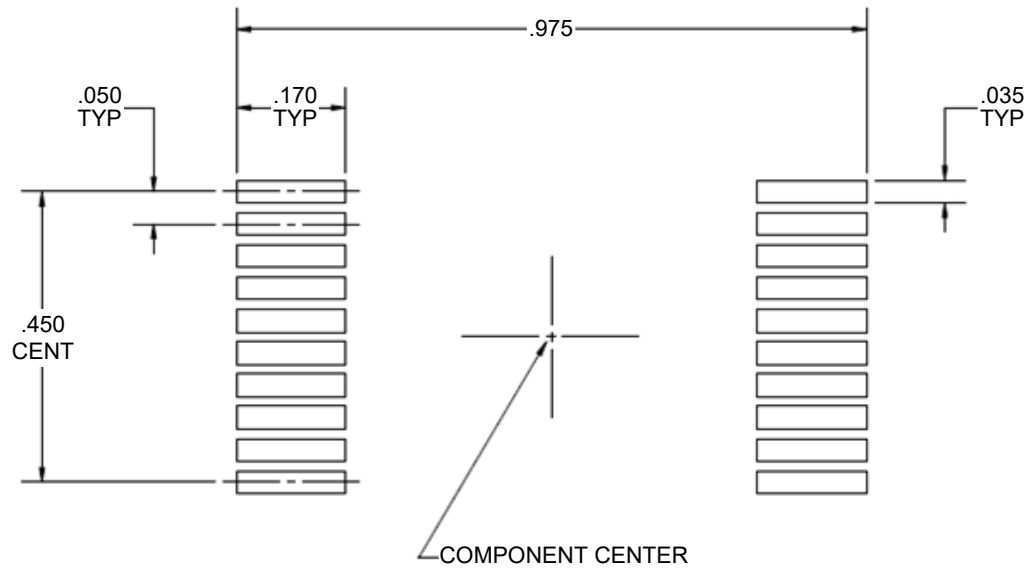
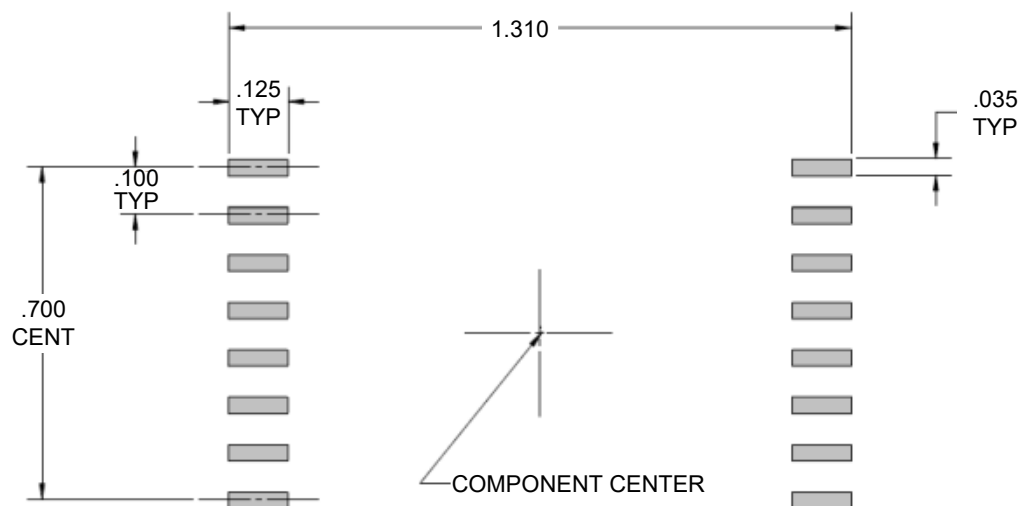


Figure 7-2. Model 1721



8. Revision History

Revision	Date	Description
B	03/2026	- Updated Hi-Rel Standard revision to E - Minor formatting and grammar changes throughout - Added support information to General - Replaced DOC204268 with DOC207984 in the first row of Table 1-3 Other - Updated junction temperature in Section 2.3 Absolute Maximum Ratings - Updated the unit of measurement in Section 3.1.4 Radiation - Added terminal strength information to Section 3.1.5 Packages - Added Premium Q to row B of Table 4-2 Design Pedigree - Updated Section 4.2 Optional Design, Test and Data Parameters - Added cross reference to line b - Added MIL-HDBK information to line i - Added DPA leak information to line n - Added destruct specimens to Section 4.2.1 NASA EEE-INST-002 Compliance - Added destruct specimens to Section 4.4 Deliverable Data line c - Added ANSI/ESD to Section 5.1 Packaging - Added an example to Section 6.1.3 Output Frequency - Renamed Section 6.2 Optional Design, Test and Data Parameters to Electrical Characteristics and Test Parameters - Added note 2 to Table 6-1 Item Identification and Package Outline - Incorporated notes into tables - Updated Frequency Range value in Table 6-2 Electrical Performance Characteristics - Removed fast/slow start from Table 6-3 Electrical Test Parameters - Added note 4 to Table 6-5 Test Matrix - Updated Figure 6-4 Model 1720 Package Outline and I/O Connection - Updated Figure 6-6 Model 1721 Package Outline and I/O Connections - Moved Recommended Land Patterns from Appendix to Section 7.0
A	07/2025	Converted Vectron Hi-Rel Standard revision D to Microchip branding with document number DS00006070 revision A. Minor text changes throughout.

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